

11-17-1998



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100900862

To the Honorable Commissioner of Patents and Trademarks, record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

PARK, Jong-min  
LEE, Sang-woo  
YOO, Byoung-juMLO  
11-3-98

## 2. Name and address of receiving party(ies):

Name: Samsung Electronics Co., Ltd.

Address: 416, Maetan-dong, Paldal-gu,

JCS11 U.S. PTO  
09/185089  
11/03/98

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

## 3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

City: Suwon-city, Kyungki-do State/Prov.: \_\_\_\_\_

Country: Republic of Korea ZIP: \_\_\_\_\_

Execution Date: October 16, 1998

Additional name(s) &amp; address(es)

☐ Yes ☒ No

## 4. Application number(s) or registration numbers(s):

09/185,089

If this document is being filed together with a new application, the execution date of the application is: October 16, 1998

Patent Application No.

Filing date

B. Patent No.(s)

Additional numbers

☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: SUSAN S. MORSE

Registration No. 35,292

Address: JONES &amp; VOLENTINE, L.L.P.

12200 SUNRISE VALLEY DRIVE, SUITE 150

City: RESTON

State/Prov.: VA

Country: U.S.A.

ZIP: 20191

## 6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

## 8. Deposit account number:

50-0238

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

SUSAN S. MORSE

Name of Person Signing

Signature

NOV. 3, 1998

Date

3

Total number of pages including cover sheet, attachments, and

# ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)  
of Inventor(s) Jong-min PARK  
Sang-woo LEE and  
Byoung-ju YOO

the undersigned hereby sell(s) and assign(s) to

Insert Name(s)  
of Assignee(s) SAMSUNG ELECTRONICS CO., LTD.  
of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

Address (hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of  
Invention METHOD OF MANUFACTURING BARRIER METAL FILM OF SEMICONDUCTOR DEVICE, METHOD  
OF MANUFACTURING METAL INTERCONNECTION FILM OF SEMICONDUCTOR DEVICE USING  
THE SAME AND APPARATUS FORMED THEREBY

Date of Signing  
of Application for which an application for patent in the United States of America has been executed by the undersigned  
on October 16, 1998

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Raymond C. Jones, Reg. No. 34,631 and Adam C. Volentine, Reg. No. 33,289, members of the firm of JONES & VOLENTINE, L.L.P. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 10/16/98, Name of Inventor Jongmin Park  
Jong-min PARK  
Date 10/16/98, Name of Inventor Sang Woo Lee  
Sang-woo LEE  
Date 10/16/98, Name of Inventor Byoung-ju YOO  
Byoung-ju YOO  
Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or recorded.)

Witness \_\_\_\_\_

Witness \_\_\_\_\_

### ACKNOWLEDGMENT

\_\_\_\_\_  
\_\_\_\_\_  
} ss

This \_\_\_\_\_ day of \_\_\_\_\_, 19\_\_\_\_, before me  
personally came the above-named \_\_\_\_\_

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL

\_\_\_\_\_  
Official Signature

\_\_\_\_\_  
Official Title

\*\*\*\*\*

Applicant Reference No.: SS-11405-US Atty Docket No.: SEC.468

Serial No.: \_\_\_\_\_ Filing Date: \_\_\_\_\_